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XINBOLE

Product Specification

XBLW SN74LS245

Octal Bus Transceiver; 3-state

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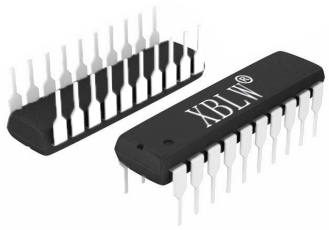
Description

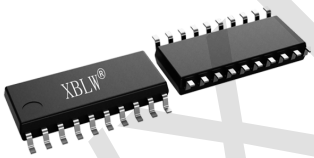
The SN74LS245 is a 8-bit transceiver with 3-state outputs. The device features an output enable ($\overline{OE}$) and send/receive (DIR) for direction control. A HIGH on $\overline{OE}$ causes the outputs to assume a high-impedance OFF-state. Inputs include clamp diodes. This enables the use of current limiting resistors to interface inputs to voltages in excess of V_{CC}.

Features

- Octal bidirectional bus interface
- Non-inverting 3-state outputs
- Specified from -20℃ to +85℃
- Packaging information: DIP-20/SOP-20/TSSOP-20/SOIC-20-208mil



DIP-20



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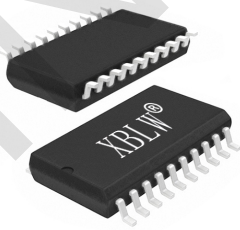
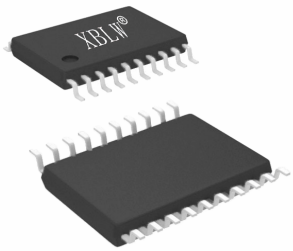


SOP-20



TSSOP-20

Ordering Information

Product Model	Package Type	Marking	Packing	Packing Qty
XBLW SN74LS245N	DIP-20	74LS245N	Tube	720Pcs/Box
XBLW SN74LS245DTR	SOP-20	74LS245	Tape	2000Pcs/Reel
XBLW SN74LS245TDTR	TSSOP-20	74LS245	Tape	2000Pcs/Reel
XBLW SN74LS245NSDTR	SOIC-20-208mil	74LS245	Tape	2000Pcs/Reel

Block Diagram

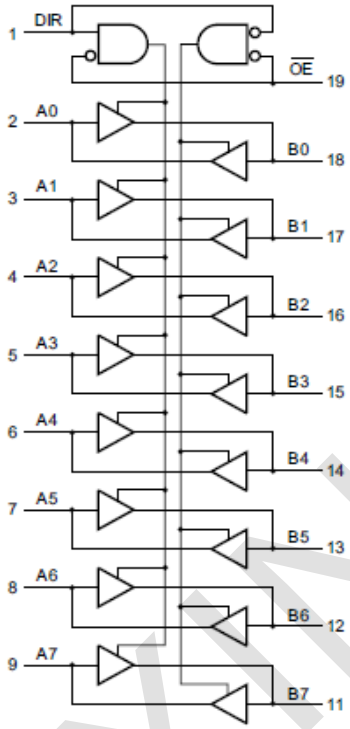


Figure 1. Logic symbol

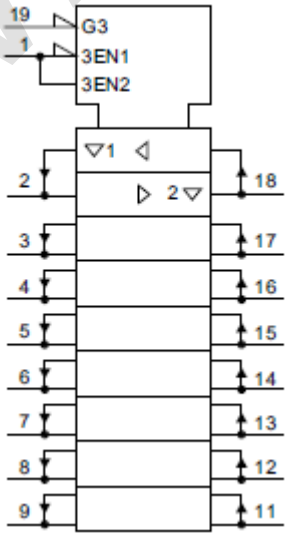
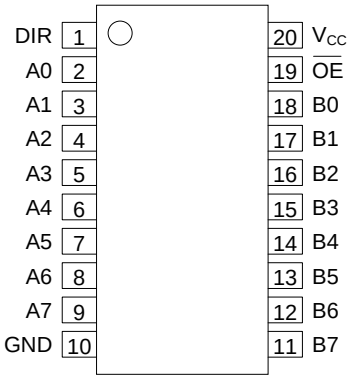


Figure 2. IEC logic symbol

Pin Configurations



Pin Description

Pin No.	Pin Name	Description
1	DIR	direction control
2	A0	data input/output
3	A1	data input/output
4	A2	data input/output
5	A3	data input/output
6	A4	data input/output
7	A5	data input/output
8	A6	data input/output
9	A7	data input/output
10	GND	ground (0V)
11	B7	data input/output
12	B6	data input/output
13	B5	data input/output
14	B4	data input/output
15	B3	data input/output
16	B2	data input/output
17	B1	data input/output
18	B0	data input/output
19	$\overline{OE}$	output enable input (active LOW)
20	V_{CC}	supply voltage

Function Table

Input		Output	
$\overline{OE}$	DIR	An	Bn
L	L	A=B	input
L	H	input	B=A
H	X	Z	Z

Note: H=HIGH voltage level; L=LOW voltage level; X=don't care; Z=high-impedance OFF-state.

Electrical Parameter

Absolute Maximum Ratings

(Voltages are referenced to GND(ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions		Min.	Max.	Unit
supply voltage	V_{CC}	-		-0.5	+7.0	V
input clamping current	I_{IK}	V_I < -0.5V or V_I > V_{CC}+0.5V		-	±20	mA
output clamping current	I_{OK}	V_O < -0.5V or V_O > V_{CC}+0.5V		-	±20	mA
output current	I_O	-0.5V < V_O < V_{CC}+0.5V		-	±35	mA
supply current	I_{CC}	-		-	70	mA
ground current	I_{GND}	-		-70	-	mA
storage temperature	T_{stg}	-		-65	+150	℃
total power dissipation	P_{tot}	-		-	500	mW
soldering temperature	T_L	10s	DIP	245		℃
			SOP/TSSOP/DHVQFN	260		℃

Recommended Operating Conditions

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
supply voltage	V_{CC}	-	2.0	5.0	6.0	V
input voltage	V_I	-	0	-	V_{CC}	V
output voltage	V_O	-	0	-	V_{CC}	V
input transition rise and fall rate	Δt/ΔV	V_{CC}=2.0V	-	-	625	ns/V
		V_{CC}=4.5V	-	1.67	139	ns/V
		V_{CC}=6.0V	-	-	83	ns/V
ambient temperature	T_{amb}	-	-20	-	+85	℃

Electrical Characteristics

DC Characteristics 1

(T_{amb}=25℃, voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions		Min.	Typ.	Max.	Unit
HIGH-level input voltage	V_{IH}	V_{CC}=2.0V		1.5	1.2	-	V
		V_{CC}=4.5V		3.15	2.4	-	V
		V_{CC}=6.0V		4.2	3.2	-	V
LOW-level input voltage	V_{IL}	V_{CC}=2.0V		-	0.8	0.5	V
		V_{CC}=4.5V		-	2.1	1.35	V
		V_{CC}=6.0V		-	2.8	1.8	V
HIGH-level output voltage	V_{OH}	V_I=V_{IH} or V_{IL}	I_O=-20uA; V_{CC}=2.0V	1.9	2.0	-	V
			I_O=-20uA; V_{CC}=4.5V	4.4	4.5	-	V
			I_O=-20uA; V_{CC}=6.0V	5.9	6.0	-	V
			I_O=-6.0mA; V_{CC}=4.5V	3.98	4.32	-	V
			I_O=-7.8mA; V_{CC}=6.0V	5.48	5.81	-	V
LOW-level output voltage	V_{OL}	V_I=V_{IH} or V_{IL}	I_O=20uA; V_{CC}=2.0V	-	0	0.1	V
			I_O=20uA; V_{CC}=4.5V	-	0	0.1	V
			I_O=20uA; V_{CC}=6.0V	-	0	0.1	V
			I_O=6.0mA; V_{CC}=4.5V	-	0.15	0.26	V
			I_O=7.8mA; V_{CC}=6.0V	-	0.16	0.26	V
input leakage current	I_I	V_I=V_{CC} or GND; V_{CC}=6.0V		-	-	±1.0	uA
OFF-state output current	I_{OZ}	V_I=V_{IH} orV_{IL}; V_{CC}=6.0V; V_O=V_{CC} or GND		-	-	±1.0	uA
supply current	I_{CC}	V_I=V_{CC} or GND; I_O=0A; V_{CC}=6.0V		-	-	8.0	uA
input capacitance	C_I	-		-	3.5	-	pF
input/output capacitance	$C_{I/O}$	-		-	10	-	pF

DC Characteristics 2

(T_{amb}=-20℃ to +85℃, voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions		Min.	Typ.	Max.	Unit
HIGH-level input voltage	V_{IH}	V_{CC}=2.0V		1.5	-	-	V
		V_{CC}=4.5V		3.15	-	-	V
		V_{CC}=6.0V		4.2	-	-	V
LOW-level input voltage	V_{IL}	V_{CC}=2.0V		-	-	0.5	V
		V_{CC}=4.5V		-	-	1.35	V
		V_{CC}=6.0V		-	-	1.8	V
HIGH-level output voltage	V_{OH}	V_I=V_{IH} or V_{IL}	I_O=-20uA; V_{CC}=2.0V	1.9	-	-	V
			I_O=-20uA; V_{CC}=4.5V	4.4	-	-	V
			I_O=-20uA; V_{CC}=6.0V	5.9	-	-	V
			I_O=-6.0mA; V_{CC}=4.5V	3.84	-	-	V
			I_O=-7.8mA; V_{CC}=6.0V	5.34	-	-	V
LOW-level output voltage	V_{OL}	V_I=V_{IH} or V_{IL}	I_O=20uA; V_{CC}=2.0V	-	-	0.1	V
			I_O=20uA; V_{CC}=4.5V	-	-	0.1	V
			I_O=20uA; V_{CC}=6.0V	-	-	0.1	V
			I_O=6.0mA; V_{CC}=4.5V	-	-	0.33	V
			I_O=7.8mA; V_{CC}=6.0V	-	-	0.33	V
input leakage current	I_I	V_I=V_{CC} or GND; V_{CC}=6.0V		-	-	±1.0	uA
OFF-state output current	I_{OZ}	V_I=V_{IH} or$V_{IL;}$ V_{CC}=6.0V; V_O=V_{CC} or GND		-	-	±5.0	uA
supply current	I_{CC}	V_I=V_{CC} or GND; I_O=0A; V_{CC}=6.0V		-	-	80	uA

AC Characteristics 1

(T_{amb}=25℃, voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions		Min.	Typ.	Max.	Unit
An to Bn or Bn to An propagation delay	t_{PLH}, t_{PHL}	see Figure 4	V_{CC}=2.0V	-	25	90	ns
			V_{CC}=4.5V	-	9	18	ns
			V_{CC}=5.0V; C_L=15pF	-	7	-	ns
			V_{CC}=6.0V	-	7	15	ns
$\overline{OE}$ to An or Bn enable time	t_{PZL}, t_{PZH}	see Figure 5	V_{CC}=2.0V	-	30	150	ns
			V_{CC}=4.5V	-	11	30	ns
			V_{CC}=6.0V	-	9	26	ns
$\overline{OE}$ to An or Bn disable time	t_{PLZ}, t_{PHZ}	see Figure 5	V_{CC}=2.0V	-	41	150	ns
			V_{CC}=4.5V	-	15	30	ns
			V_{CC}=6.0V	-	12	26	ns
transition time	t_{THL}, t_{TLH}	see Figure 4	V_{CC}=2.0V	-	14	60	ns
			V_{CC}=4.5V	-	5	12	ns
			V_{CC}=6.0V	-	4	10	ns

AC Characteristics 2

(T_{amb}=-20℃ to +85℃, voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions		Min.	Typ.	Max.	Unit
An to Bn or Bn to An propagation delay	t_{PLH}, t_{PHL}	see Figure 4	V_{CC}=2.0V	-	-	115	ns
			V_{CC}=4.5V	-	-	23	ns
			V_{CC}=6.0V	-	-	20	ns
$\overline{OE}$ to An or Bn enable time	t_{PZL}, t_{PZH}	see Figure 5	V_{CC}=2.0V	-	-	190	ns
			V_{CC}=4.5V	-	-	38	ns
			V_{CC}=6.0V	-	-	33	ns
$\overline{OE}$ to An or Bn disable time	t_{PLZ}, t_{PHZ}	see Figure 5	V_{CC}=2.0V	-	-	190	ns
			V_{CC}=4.5V	-	-	38	ns
			V_{CC}=6.0V	-	-	33	ns
transition time	t_{THL}, t_{TLH}	see Figure 4	V_{CC}=2.0V	-	-	75	ns
			V_{CC}=4.5V	-	-	15	ns
			V_{CC}=6.0V	-	-	13	ns

Measurement Points

Type	Input	Output
	V_M	V_M
SN74LS245	0.5×V_{CC}	0.5×V_{CC}

Test Data

Type	Input		Load		S1 position		
	V_I	t_r ,t_f	C_L	R_L	t_{PHL}, t_{PLH}	t_{PZH}, t_{PHZ}	t_{PZL}, t_{PLZ}
SN74LS245	V_{CC}	6ns	15pF, 50pF	1kΩ	open	GND	V_{CC}

Testing Circuit

AC Testing Circuit

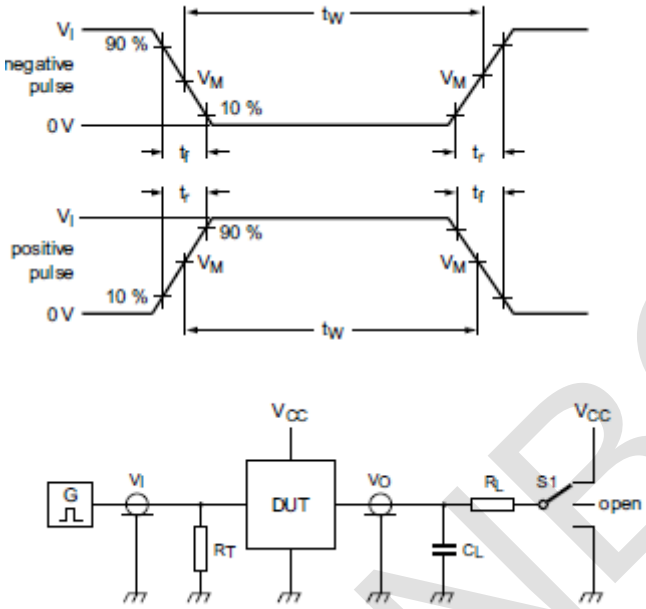


Figure 3. Test circuit for measuring switching times

Definitions for test circuit: R_L=Load resistance.

C_L=Load capacitance including jig and probe capacitance.

R_T=Termination resistance should be equal to the output impedance Z_o of the pulse generator. S1=Test selection switch.

AC Testing Waveforms

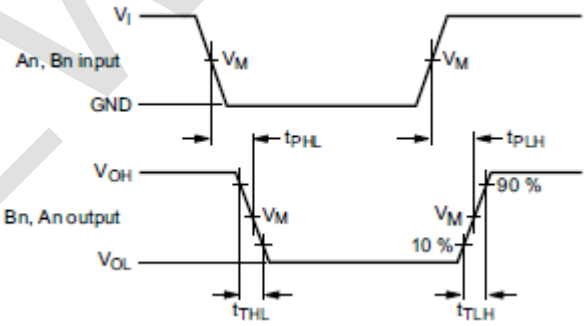


Figure 4. Input (An, Bn) to output (Bn, An) propagation delays and output transition times

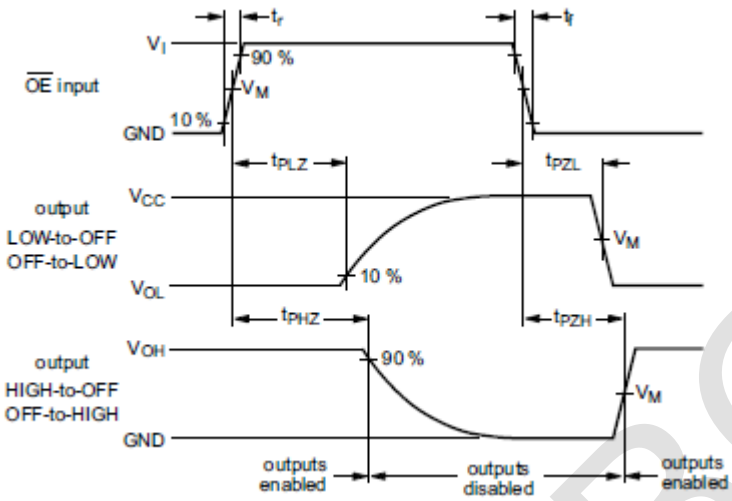
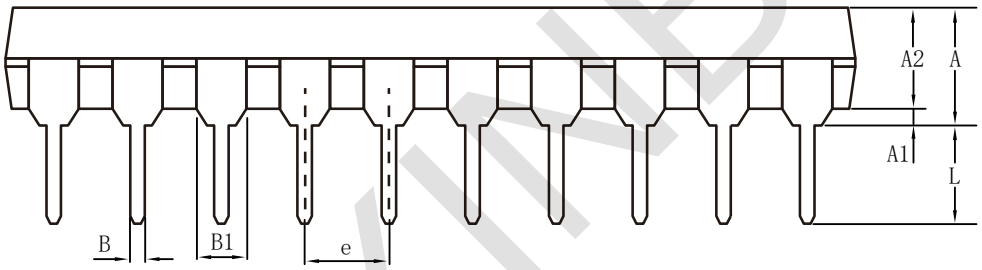


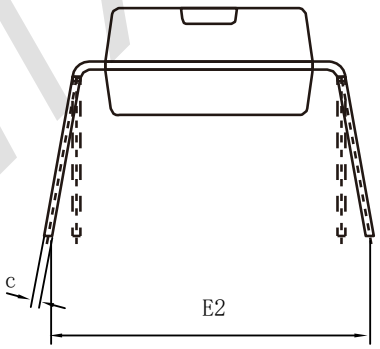
Figure 5. 3-state enable and disable times

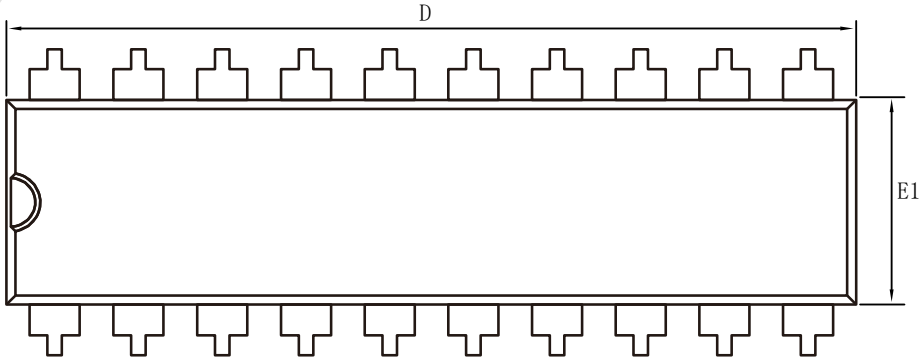
Package Information

· DIP-20

Size / Symbol	Dimensions In Millimeters		Size / Symbol	Dimensions In Inches	
	Min(mm)	Max(mm)		Min(in)	Max(in)
A	3.600	5.330	A	0.142	0.210
A1	0.510		A1	0.020	
A2	3.200	3.600	A2	0.126	0.142
B	0.360	0.530	B	0.014	0.021
B1	1.52(BSC)		B1	0.060(BSC)	
c	0.204	0.360	c	0.008	0.014
D	25.70	26.54	D	1.010	1.040
E1	6.200	6.750	E1	0.244	0.260
E2	7.620	9.300	E2	0.300	0.366
e	2.54(BSC)		e	0.100(BSC)	
L	3.000	3.600	L	0.118	0.142

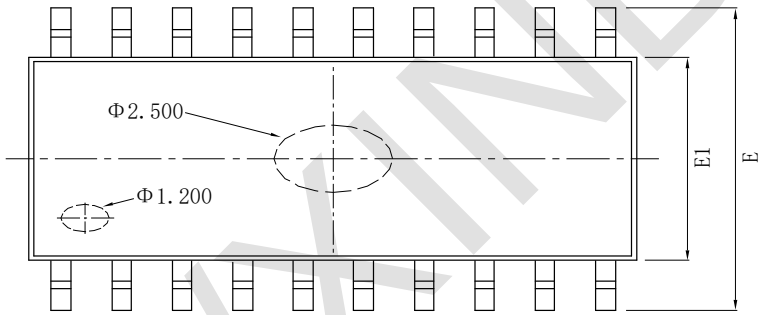


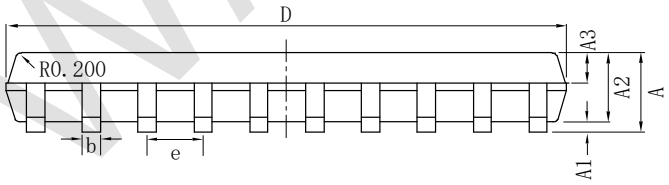


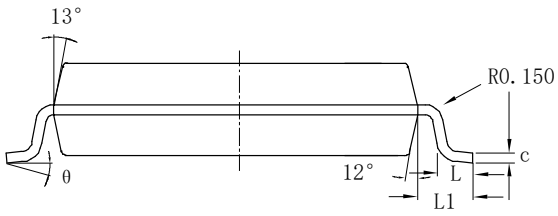


· SOIC-20-208mil

Size / Symbol	Dimensions In Millimeters		Size / Symbol	Dimensions In Inches	
	Min(mm)	Max(mm)		Min(in)	Max(in)
A		2.000	A		0.079
A1	0.050	0.250	A1	0.002	0.010
A2	1.650	1.850	A2	0.065	0.073
b	0.350	0.550	b	0.014	0.022
c	0.150	0.200	c	0.006	0.008
D	12.25	12.65	D	0.482	0.498
E	7.600	8.000	E	0.299	0.315
E1	5.100	5.500	E1	0.201	0.217
e	1.270		e	0.050	
L	0.550	0.950	L	0.022	0.037
L1	1.250		L1	0.049	
θ	0°	8°	θ	0°	8°

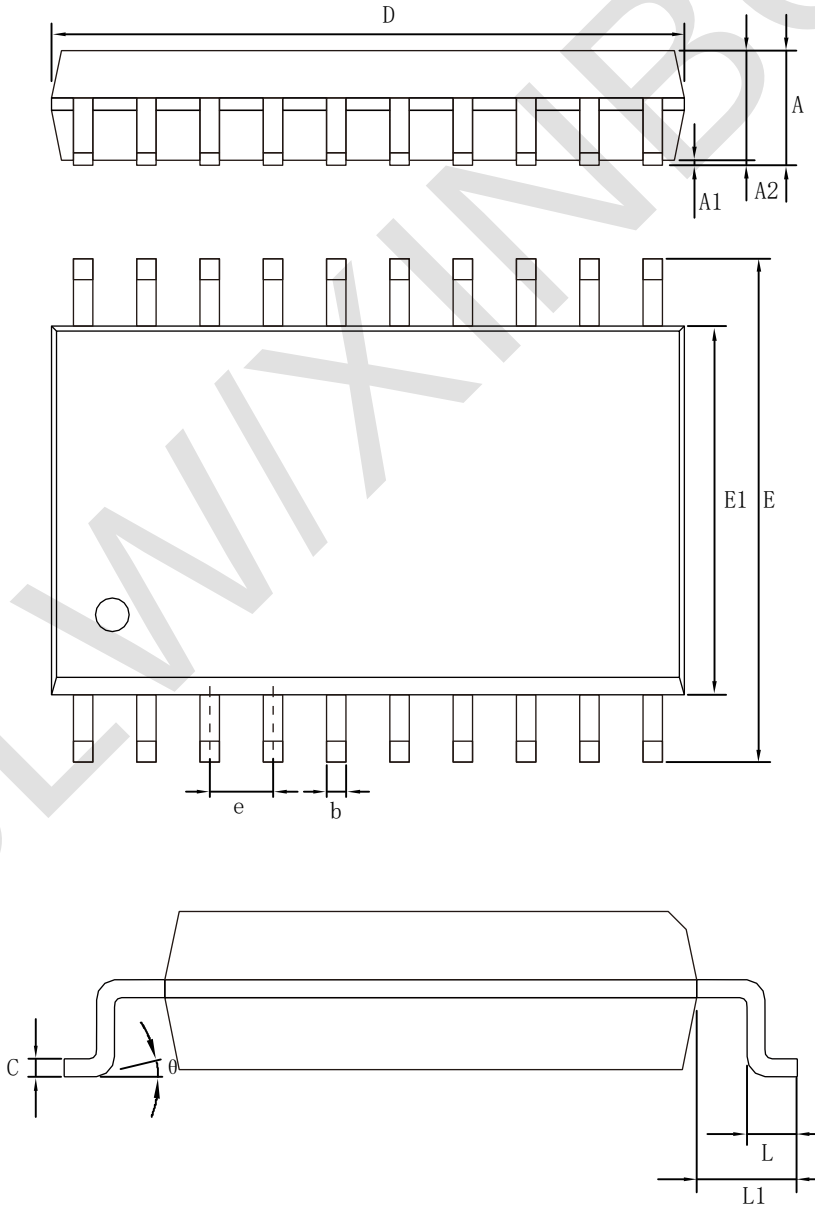






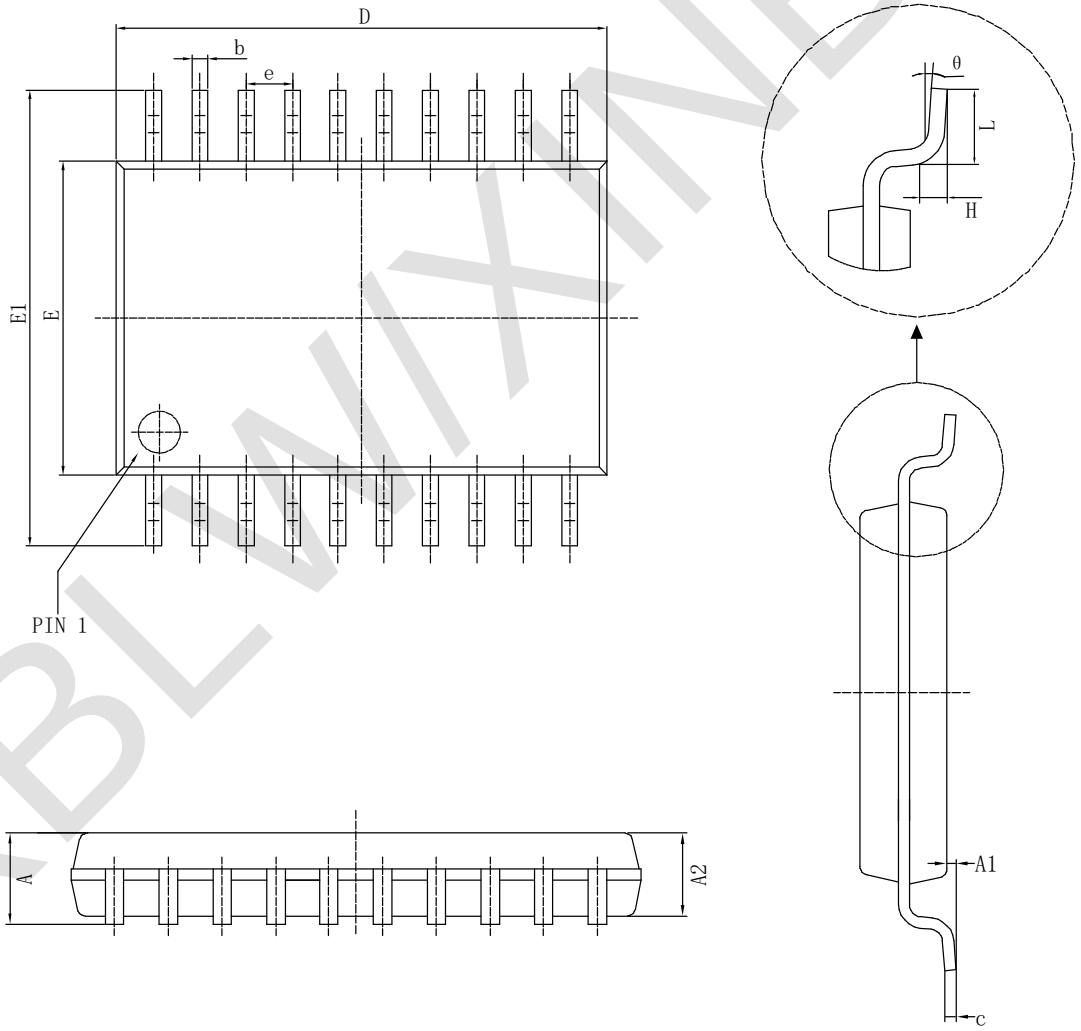
· SOP-20

Size / Symbol	Dimensions In Millimeters		Size / Symbol	Dimensions In Inches	
	Min(mm)	Max(mm)		Min(in)	Max(in)
A	2.470	2.650	A	0.097	0.104
A1	0.050	0.300	A1	0.002	0.012
A2	2.200	2.440	A2	0.087	0.096
b	0.350	0.500	b	0.014	0.020
c	0.150	0.300	c	0.006	0.012
D	12.54	12.94	D	0.494	0.509
E	10.00	10.60	E	0.394	0.417
E1	7.300	7.700	E1	0.287	0.303
e	1.270(BSC)		e	0.050(BSC)	
L	0.400	1.050	L	0.016	0.041
L1	1.300	1.500	L1	0.051	0.059
θ	0°	8°	θ	0°	8°



· TSSOP-20

Size / Symbol	Dimensions In Millimeters		Size / Symbol	Dimensions In Inches	
	Min(mm)	Max(mm)		Min(in)	Max(in)
D	6.400	6.600	D	0.252	0.259
E	4.300	4.500	E	0.169	0.177
b	0.190	0.300	b	0.007	0.012
c	0.090	0.200	c	0.004	0.008
E1	6.250	6.550	E1	0.246	0.258
A		1.200	A		0.047
A2	0.800	1.000	A2	0.031	0.039
A1	0.050	0.150	A1	0.002	0.006
e	0.65(BSC)		e	0.026(BSC)	
L	0.500	0.700	L	0.020	0.028
H	0.25(TYP)		H	0.01(TYP)	
θ	1°	7°	θ	1°	7°



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